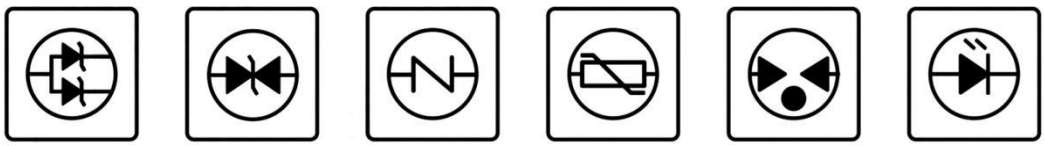
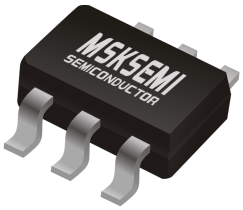
MSKSEMI
SEMICONDUCTOR



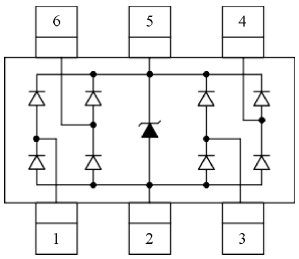
Product data sheet

PACKAGE OUTLINE



SOT-23-6

PIN CONFIGURATION



FEATURES

- ✧ Transient protection for high-speed data lines
  IEC 61000-4-2(ESD) ±20KV(Contact)
  ±25KV(Air)
  IEC 61000-4-4(EFT) 40A(5/50ns)
- ✧ Package optimized for high-speed lines
- ✧ Small package(2.9mm*2.8mm*1.1mm)
- ✧ Protects four data lines and one Vcc line
- ✧ Low capacitance: 0.20pF (I/O to I/O)
- ✧ Low leakage current
- ✧ Low clamping voltage
- ✧ Each I/O pin can withstand over 1000 ESD strikes for ±8KV contact discharge

MACHANICAL DATA

- ✧ Flammability Rating: UL 94V-0
- ✧ Terminal: Matte tin plated.
- ✧ High temperature soldering guaranteed:
- ✧ 260℃/10s
- ✧ Packaging: Tape and Reel
- ✧ Reel size: 7 inch

APPLICATIONS

- ✧ Serial ATA
- ✧ MDDI Ports
- ✧ USB 2.0/3.0 Power and Data Line Protection
- ✧ Display Ports
- ✧ High Definition Multi-Media Interface (HDMI)
- ✧ Digital Visual Interface (DVI)

ABSOLUTE MAXIMUM RATING			
Symbol	**Parameter**	**Value**	**Units**
P_{PP}	Peak Pulse Power (8/20μs)	60	W
V_{ESD}	ESD per IEC 61000-4-2 (Contact) ESD per IEC 61000-4-2 (Air)	±20 ±25	kV
T_{OPT}	Operating Temperature	-55/+125	°C
T_{STG}	Storage Temperature	-55/+150	°C

ELECTRICAL CHARACTERISTICS (Tamb=25°C)						
Symbol	**Parameter**	**Test Condition**	**Min**	**Typ**	**Max**	**Units**
V_{RWM}	Reverse Working Voltage	Any I/O pin to GND			5.0	V
V_{BR}	Reverse Breakdown Voltage	I_T = 1mA Any I/O pin to GND	6.0		9.0	V
I_R	Reverse Leakage Current	V_{RWM} = 5V Any I/O pin to GND			1.0	μA
V_C	Clamping Voltage	I_{PP} = 1A, t_p = 8/20μs Any I/O pin to GND			10	V
		I_{PP} = 4A, t_p = 8/20μs Any I/O pin to GND			15	V
		I_{PP} = 8A, t_p = 8/20μs Vcc pin to GND			15	V
C_{ESD}	Parasitic Capacitance	V_R = 0V, f = 1MHz Between I/O and I/O		0.20	0.30	pF
		V_R = 0V, f = 1MHz Between I/O and GND		0.45	0.50	pF
		V_R = 0V, f = 1MHz Between Vcc and GND		0.80		pF

Note: I/O Pins are pin 1,3,4,6. Pin 5 is Vcc. Pin 2 is GND.

ELECTRICAL CHARACTERISTICS CURVE

Fig 1 Power Derating Curve

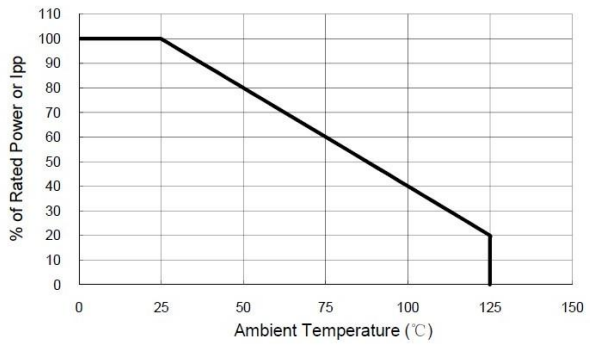


Fig 2 Clamping Voltage vs Peak Pulse Current

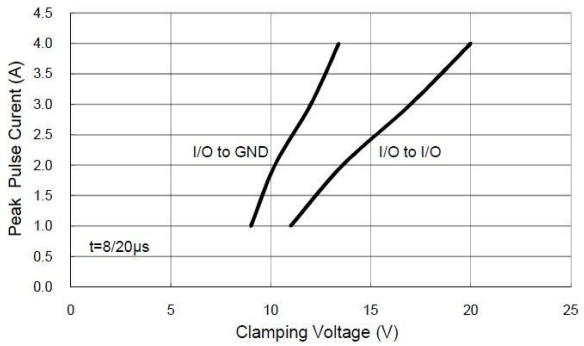


Fig 3 Voltage Sweeping of I/O to I/O

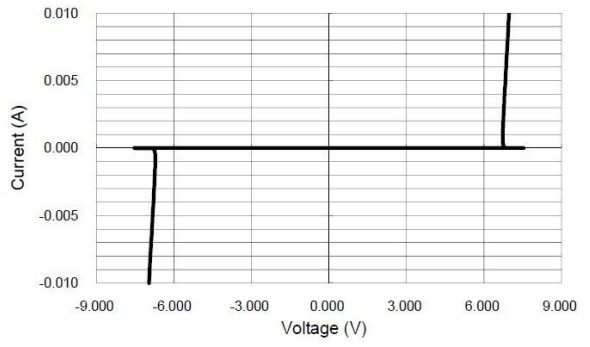


Fig 4 Voltage vs Capacitance

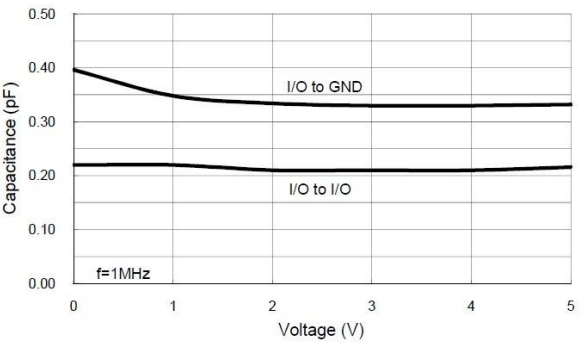


Fig 5 ESD Clamping of I/O to GND
(+8kV Contact per IEC 61000-4-2)

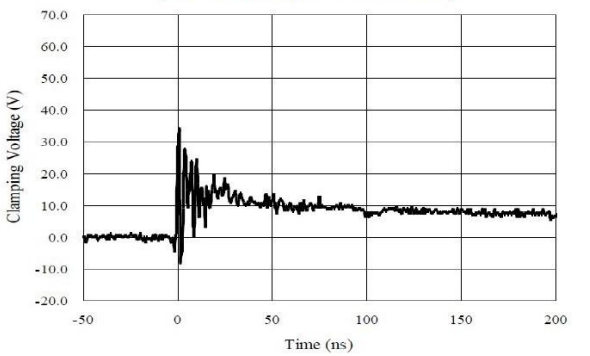
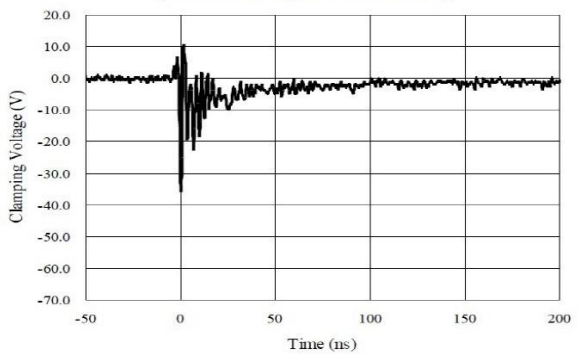
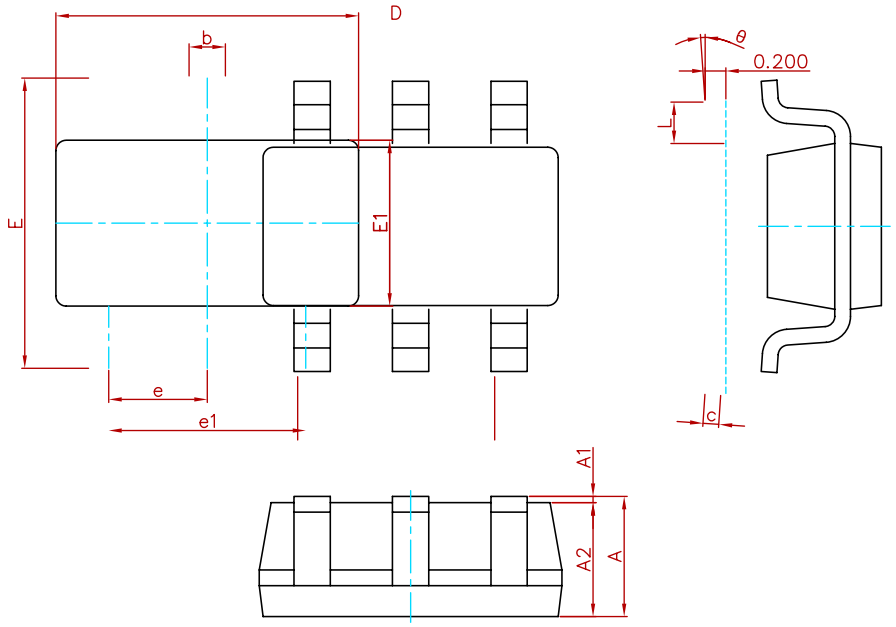


Fig 6 ESD Clamping of I/O to GND
(-8kV Contact per IEC 61000-4-2)

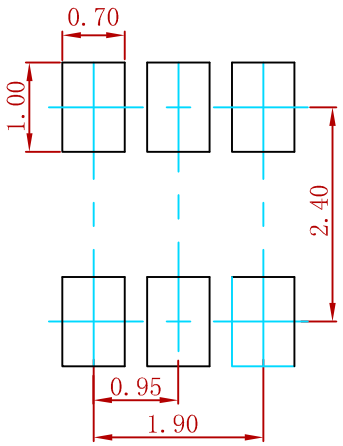


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
SRV05-4-P-T7	SOT-23-6	3000

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